

TUNGSTEN DEPOSITION

INCORPORATED BY REFERENCE

5 [0001] A PCT Request Form is filed concurrently with this specification as part of the present application. Each application that the present application claims benefit of or priority to as identified in the concurrently filed PCT Request Form is incorporated by reference herein in its entirety and for all purposes.

BACKGROUND

10 [0002] Tungsten (W) film deposition using chemical vapor deposition (CVD) techniques is an integral part of semiconductor fabrication processes. For example, tungsten films may be used as low resistivity electrical connections in the form of horizontal interconnects, vias between adjacent metal layers, and contacts between a first metal layer and the devices on a silicon substrate. Tungsten films may also be used in various memory applications, including in formation of buried wordline (bWL) architectures for
15 dynamic random access memory (DRAM), word lines for 3D NAND, and logic applications. However, the continued decrease in feature size and film thickness brings various challenges including deposition of films having good step coverage.

[0003] The background description provided herein is for the purposes of generally presenting the context of the disclosure. Work of the presently named inventors, to the
20 extent it is described in this background section, as well as aspects of the description that may not otherwise qualify as prior art at the time of filing, are neither expressly nor impliedly admitted as prior art against the present disclosure.

SUMMARY

[0004] One aspect of the disclosure relates to a method including providing a substrate
25 including a feature in a chamber; depositing a tungsten nucleation layer in the feature by performing one or more cycles of an atomic layer deposition (ALD) process, where each cycle includes: flowing one or more boron-containing reducing agent doses in the chamber, flowing one or more silicon-containing reducing agent doses in the chamber, where the one or more boron-containing reducing agent doses and the one or more
30 silicon-containing reducing agent doses are sequential reactant doses, and after flowing

the one or more boron-containing reducing agent and one or more silicon-containing reducing agent doses in the chamber, flowing one or more tungsten-containing precursor pulses in the chamber.

[0005] In some embodiments, the feature is a wordline (WL) feature in a 3-D NAND structure, the 3-D NAND structure including vertically-oriented sidewalls, a plurality of openings in the sidewalls leading to a plurality of horizontally-oriented WL features. In some embodiments, the method further includes purging the chamber between sequential reactant doses. In some embodiments, the method further includes depositing a bulk tungsten layer on the tungsten nucleation layer. In some embodiments, the bulk tungsten layer is deposited by an atomic layer deposition process using hydrogen (H₂) as a reducing agent. In some embodiments, each ALD cycle begins with a boron-containing reducing agent dose. In some embodiments, each ALD cycle begins with a silicon-containing reducing agent dose.

[0006] Another aspect of the disclosure relates to a method of filling a 3-D NAND structure. The method can include providing, in a chamber, a 3-D NAND structure including vertically-oriented sidewalls, a plurality of openings in the sidewalls leading to a plurality of horizontally-oriented wordline (WL) features; depositing a tungsten nucleation layer in the WL features by performing one or more cycles of an atomic layer deposition (ALD) process, where each cycle includes flowing one or more boron-containing reducing agent doses in the chamber, flowing one or more silane doses in the chamber; and after flowing the one or more boron-containing reducing agent and one or more silicon-containing reducing agent doses in the chamber, flowing one or more tungsten-containing precursor pulses in the chamber.

[0007] In some embodiments, the method further includes purging the chamber between sequential reactant doses. In some embodiments, the method further includes depositing a bulk tungsten layer on the tungsten nucleation layer. In some embodiments, the bulk tungsten layer is deposited by an atomic layer deposition process using hydrogen (H₂) as a reducing agent. In some embodiments, each ALD cycle begins with a boron-containing reducing agent dose. In some embodiments, each ALD cycle begins with a silicon-containing reducing agent dose.

[0008] Another aspect relates to an apparatus including a process chamber comprising

one or more process stations, each process station comprising a substrate support configured to hold a substrate; at least one outlet for coupling to a vacuum; one or more process gas inlets coupled to one or more process gas sources; and a controller for controlling operations in the apparatus, comprising machine-readable instructions for:
5 flowing one or more boron-containing reducing agent doses in the chamber, flowing one or more silane doses in the chamber; and after flowing the one or more boron-containing reducing agent and one or more silicon-containing reducing agent doses in the chamber, flowing one or more tungsten-containing precursor pulses in the chamber.

[0009] According to various embodiments, the doses may be in the same or different
10 stations.

[0010] These and other aspects are described below with reference to the Figures.

BRIEF DESCRIPTION OF DRAWINGS

[0011] Figures 1A–1H show schematic examples of features that may be filled with tungsten according to various embodiments.

15 [0012] Figures 2A and 2B show examples timing sequence diagram showing example cycles of a method for depositing a tungsten nucleation layer.

[0013] Figure 3 shows a schematic example of an apparatus including charge volumes to introduce the gas doses to the chamber that may be used to implement methods described herein.

20 [0014] Figure 4 shows a schematic example of a process system suitable for conducting deposition processes in accordance with embodiments.

[0015] Figure 5 shows a schematic example of a process station suitable for conducting deposition processes in accordance with embodiments.

DETAILED DESCRIPTION

25 [0016] Described herein are methods of filling features with tungsten and related systems and apparatus. Examples of applications include logic and memory contact fill, DRAM buried wordline fill, vertically integrated memory gate/wordline fill, and 3-D integration with through-silicon vias (TSVs). The methods described herein can be used to

fill vertical features, such as in tungsten vias, and horizontal features, such as vertical NAND (VNAND) wordlines, and The methods may be used for conformal and bottom-up or inside-out fill.

[0017] According to various embodiments, the features can be characterized by one or more of narrow and/or re-entrant openings, constrictions within the feature, and high aspect ratios. Examples of features that can be filled are depicted in Figures 1A–1C. Figure 1A shows an example of a cross-sectional depiction of a vertical feature 101 to be filled with tungsten. The feature can include a feature hole 105 in a substrate 103. The substrate may be a silicon wafer, e.g., 200-mm wafer, 300-mm wafer, 450-mm wafer, including wafers having one or more layers of material such as dielectric, conducting, or semi-conducting material deposited thereon. In some embodiments, the feature hole 105 may have an aspect ratio of at least about 2:1, at least about 4:1, at least about 6:1 or higher. The feature hole 105 may also have a dimension near the opening, e.g., an opening diameter or line width, of between about 10 nm to 500 nm, for example between about 25 nm to 300 nm. The feature hole 105 can be referred to as an unfilled feature or simply a feature. The feature, and any feature, may be characterized in part by an axis 118 that extends through the length of the feature, with vertically-oriented features having vertical axes and horizontally-oriented features having horizontal axes.

[0018] Figure 1B shows an example of a feature 101 that has a re-entrant profile. A re-entrant profile is a profile that narrows from a bottom, closed end, or interior of the feature to the feature opening. According to various embodiments, the profile may narrow gradually and/or include an overhang at the feature opening. Figure 1B shows an example of the latter, with an under-layer 113 lining the sidewall or interior surfaces of the feature hole 105. The under-layer 113 can be for example, a diffusion barrier layer, an adhesion layer, a nucleation layer, a combination of thereof, or any other applicable material. The under-layer 113 forms an overhang 115 such that the under-layer 113 is thicker near the opening of the feature 101 than inside the feature 101.

[0019] In some embodiments, features having one or more constrictions within the feature may be filled. Figure 1C shows examples of views of various filled features having constrictions. Each of the examples (a), (b) and (c) in Figure 1C includes a constriction 109 at a midpoint within the feature. The constriction 109 can be, for example, between about

15 nm–20 nm wide. Constrictions can cause pinch off during deposition of tungsten in the feature using conventional techniques, with deposited tungsten blocking further deposition past the constriction before that portion of the feature is filled, resulting in voids in the feature. Example (b) further includes a liner/barrier overhang 115 at the feature opening. Such an overhang could also be a potential pinch-off point. Example (c) includes a constriction 112 further away from the field region than the overhang 115 in example (b). As described further below, methods described herein allow void-free fill as depicted in Figure 1C.

[0020] Horizontal features, such as in 3-D memory structures, can also be filled. Figure 1D shows an example of a word line 150 in a VNAND structure 148 that includes a constriction 151. In some embodiments, the constrictions can be due to the presence of pillars in a VNAND or other structure. Figure 1E, for example, shows a plan view of pillars 125 in a VNAND structure, with Figure 1F showing a simplified schematic of a cross-sectional depiction of the pillars 125. Arrows in Figure 1E represent deposition material; as pillars 125 are disposed between an area 127 and a gas inlet or other deposition source, adjacent pillars can result in constrictions that present challenges in void free fill of an area 127.

[0021] Figure 1G provides another example of a view horizontal feature, for example, of a VNAND or other structure including pillar constrictions 151. The example in Figure 1G is open-ended, with material to be deposited able to enter laterally from two sides as indicated by the arrows. (It should be noted that example in Figure 1G can be seen as a 2-D rendering 3-D features of the structure, with the Figure 1G being a cross-sectional depiction of an area to be filled and pillar constrictions shown in the figure representing constrictions that would be seen in a plan rather than cross-sectional view.) In some embodiments, 3-D structures can be characterized with the area to be filled extending along three dimensions (e.g., in the X, Y and Z-directions in the example of Figure 1F), and can present more challenges for fill than filling holes or trenches that extend along one or two dimensions. For example, controlling fill of a 3-D structure can be challenging as deposition gasses may enter a feature from multiple dimensions. The methods may also be used to fill interconnects to tungsten wordlines as shown in Figure 1H, where interconnect features 170 may be filled with tungsten to connect to the tungsten

wordlines 172. Examples of feature fill for horizontally-oriented and vertically-oriented features are described below. It should be noted that in most cases, the examples applicable to both horizontally-oriented or vertically-oriented features.

[0022] Distribution of a material within a feature may be characterized by its step coverage. For the purposes of this description, “step coverage” is defined as a ratio of two thicknesses, e.g., the thickness of the material inside the feature divided by the thickness of the material near the opening. For purposes of this description, the term “inside the feature” represents a middle portion of the feature located about the middle point of the feature along the feature’s axis, e.g., an area between about 25% and 75% of the distance or, in certain embodiments, between about 40% and 60% of the distance along the feature’s depth measured from the feature’s opening, or an end portion of the feature located between about 75% and 95% of the distance along the feature’s axis as measured from the opening. The term “near the opening of the feature” or “near the feature’s opening” represents a top portion of the feature located within 25% or, more specifically, within 10% of the opening’s edge or other element representative of the opening’s edge. Step coverage of over 100% can be achieved, for example, by filling a feature wider in the middle or near the bottom of the feature than at the feature opening or where a thicker film is deposited within the feature than on or near the opening.

[0023] The methods described herein involve deposition of a tungsten nucleation layer prior to deposition of a bulk layer. A nucleation layer is typically a thin conformal layer that facilitates subsequent deposition of bulk tungsten-containing material thereon. According to various embodiments, a nucleation layer may be deposited prior to any fill of the feature and/or at subsequent points during fill of the feature with tungsten or a tungsten-containing material.

[0024] In certain implementations, the nucleation layer is deposited sequentially injecting pulses of a reducing agent, optional purge gases, and tungsten-containing precursor from the reaction chamber. The process is repeated in a cyclical fashion until the desired thickness is achieved. Nucleation layer thickness can depend on the nucleation layer deposition method as well as the desired quality of bulk deposition. In general, nucleation layer thickness is sufficient to support high quality, uniform bulk deposition. Examples may range from 5Å-100Å, or 12Å-50Å.

[0025] Atomic layer deposition (ALD) techniques differ from chemical vapor deposition (CVD) techniques in which reactants are introduced together. In certain embodiments, the nucleation layer is deposited by an ALD process in which pulses of a reducing agent, optional purge gases, and tungsten-containing precursor are sequentially injected into and
5 purged from the reaction chamber. The process is repeated in a cyclical fashion until the desired thickness is achieved.

[0026] Described herein are methods of depositing a tungsten nucleation layer that achieve good step coverage, low resistivity, and good fill. The methods involve using both a boron-containing reducing agent and a silicon-containing reducing agent to react with a
10 tungsten-containing precursor in an ALD process.

[0027] ALD tungsten processes may use two half-reactions enabled by the sequential delivery of two or more co-reactants. One co-reactant acts to functionalize the surface and permit the adsorption of tungsten-containing species to the substrate. Subsequent cycles result in the deposition of a conformal thin film.

[0028] In some embodiments, a mixture of a boron-containing reducing agent and a silicon-containing reducing agent is pulsed alternately with a tungsten-containing precursor. One ALD cycle may be expressed as (B+S)/purge/W/purge, with B being a boron-containing reducing agent (e.g., diborane, B_2H_6), S being a silicon-containing reducing agent (e.g., silane, SiH_4), and W being a tungsten-containing precursor (e.g.,
20 WF_6). A purge between reactant pulses may be performed, with argon (Ar) or other inert gas being used to purge.

[0029] In some embodiments, a pulse of a boron-containing reducing agent and a silicon-containing reducing agent delivered sequentially in a cycle such that one cycle may be represented as B/S/purge/W/purge or as S/B/purge/W/purge. According to various
25 embodiments, there may or may not be a purge between B and S pulses. Thus, the cycle may be represented as B/purge/S/purge/W/purge or S/purge/B/purge/W/purge.

[0030] By using both boron-containing and silicon-containing reducing agents, the resulting tungsten has lower resistivity than silicon-containing reducing agent only processes and lower void percentage and stress than boron-containing reducing only
30 processes. Large grains from a boron-only process result in low resistivity but cause voids

when two tungsten surfaces come together. Using silicon-containing reducing agent mitigates the voids without sacrificing low resistivity. Better step coverage and lower void percentage reduce the line bending and stress.

[0031] Substrate temperatures are low enough to suppress decomposition of the boron-containing reducing agent and may be below about 350°C, for example between about 250°C and 300°C. Even at these relatively low temperatures, diborane is susceptible to decomposition. B_2H_6 can decompose during the ALD cycle (e.g., $B_2H_6 \rightarrow 2/3B_3 + 3H_2$) which degrades the step coverage of the process. By using B_2H_6 and SiH_4 , the decomposition of B_2H_6 is suppressed, improving step coverage. Deposition using silane typically uses higher temperatures; however, the temperature used for silane can be lowered with the use of the boron-containing reducing agent as well.

[0032] Examples of chamber pressure are between 10 torr and 60 torr, or 10 torr and 40 torr. In some embodiments, it is above 10 torr. It may also be below 10 torr to reduce fluorine incorporation, for example.

[0033] Figures 2A and 2B show examples timing sequence diagram showing example cycles of a method for depositing a tungsten nucleation layer, with Figure 2A showing a co-flow of diborane and silane and Figure 2B showing diborane and silane delivered in sequential consecutive reactant pulses.

[0034] Various modifications to the timing diagrams in Figures 2A and 2B may be made. In some embodiments, hydrogen may be flowed during the diborane and/or silane pulses. Flowing hydrogen during the diborane pulse can further suppress decomposition and help with step coverage.

[0035] In Figure 2B, one or both of the diborane and silane pulses may be multi-pulses. For example, while Figure 2B shows B/S/W (not including purges), a cycle could also be $x(B)/y(S)/z(W)$, wherein x, y, and z are integers greater than zero. If x is 2, and y and z are 1, the sequence would be B/B/S/W, with optional purges between the pulses. In this manner, the ratio of boron to silicon may be tuned.

[0036] Similarly, silane may be first, e.g., $x(S)/y(B)/z(W)$ wherein x, y, and z are integers greater than zero. In some embodiments, multiple boron-containing reducing agent or silicon-containing reducing agent pulses may be interspersed with the pulses of the other

reducing agent (e.g., B/S/B/S/W).

[0037] Still further, in some embodiments, the one or more tungsten-containing precursor pulses may precede the reducing agent pulses in each cycle.

[0038] The tungsten-containing precursor may be a tungsten halide that can be reduced
5 by a boron-containing reducing agent including tungsten fluorides (e.g., WF₆) and tungsten chlorides (e.g., WCl₅ and WCl₆). While diborane is described above as the boron-containing reducing agent, the method may be implemented other boron-containing reducing agents. Examples include hexaborane and triborane. While silane is described above as the boron-containing reducing agent, the method may be implemented other
10 silicon-containing reducing agents. Examples include disilane.

[0039] It should be noted that boron and/or silicon is generally not incorporated into the tungsten film at appreciable levels.

Bulk deposition

[0040] After nucleation layer deposition, the feature may be filled with a bulk tungsten
15 layer. In some implementations, tungsten bulk deposition can occur by a CVD process in which a reducing agent and a tungsten-containing precursor are flowed into a deposition chamber to deposit a bulk fill layer in the feature. In some implementations, tungsten bulk deposition can occur by an ALD process in which a reducing agent and a tungsten-containing precursor are sequentially introduced into a deposition chamber to deposit a
20 bulk fill layer in the feature. If CVD is used, this operation can involve flowing the reactants continuously until the desired amount is deposited. In certain implementations, the CVD operation may take place in multiple stages, with multiple periods of continuous and simultaneous flow of reactants separated by periods of one or more reactant flows diverted. Still further, inhibition of tungsten growth and/or etching may be performed
25 during feature fill.

[0041] Various tungsten containing gases including, but not limited to, WF₆, WCl₆, and W(CO)₆ can be used as the tungsten-containing precursor. In certain implementations, the tungsten-containing precursor is a halogen-containing compound, such as WF₆. In certain implementations, the reducing agent is hydrogen gas, though other reducing
30 agents may be used including silane (SiH₄), disilane (Si₂H₆) hydrazine (N₂H₄), diborane

(B₂H₆) and germane (GeH₄). In many implementations, hydrogen gas is used as the reducing agent in the CVD process. In some other implementations, a tungsten precursor that can decompose to form a bulk tungsten layer can be used. Bulk deposition may also occur using other types of processes including ALD processes.

- 5 **[0042]** Deposition may proceed according to various implementations until a certain feature profile is achieved and/or a certain amount of tungsten is deposited. In some implementations, the deposition time and other relevant parameters may be determined by modeling and/or trial and error. For example, for an initial deposition for an inside out fill process in which tungsten can be conformally deposited in a feature until pinch-off, it
- 10 may be straightforward to determine based on the feature dimensions the tungsten thickness and corresponding deposition time that will achieve pinch-off. In some implementations, a process chamber may be equipped with various sensors to perform in-situ metrology measurements for end-point detection of a deposition operation. Examples of in-situ metrology include optical microscopy and X-Ray Fluorescence (XRF) for
- 15 determining thickness of deposited films.

- [0043]** It should be understood that the tungsten films described herein may include some amount of other compounds, dopants and/or impurities such as nitrogen, carbon, oxygen, boron, phosphorous, sulfur, silicon, germanium and the like, depending on the particular precursors and processes used. The tungsten content in the film may range from
- 20 20% to 100% (atomic) tungsten. In many implementations, the films are tungsten-rich, having at least 50% (atomic) tungsten, or even at least about 60%, 75%, 90%, or 99% (atomic) tungsten. In some implementations, the films may be a mixture of metallic or elemental tungsten (W) and other tungsten-containing compounds such as tungsten carbide (WC), tungsten nitride (WN), etc.

- 25 **[0044]** CVD and ALD deposition of these materials can include using any appropriate precursors. For example, CVD and ALD deposition of tungsten nitride can include using halogen-containing and halogen-free tungsten-containing and nitrogen-containing compounds.

Experimental

- 30 **[0045]** ALD of tungsten nucleation layers was performed in a 3D-NAND structures of

using Processes A and B. Void percentage was measured at various wordline (WL) heights. The ALD tungsten nucleation process was followed by a bulk tungsten deposition process that was the same for all processes.

[0046] Process A: multiple cycles of (B₂H₆ – Ar purge – WF₆ – Ar purge)

5 **[0047]** Process B: multiple cycles of (B₂H₆ – Ar purge – SiH₄ – Ar purge – WF₆)

	Process A	Process B
Top void %	1.2% +- 1.5%	6.9% +- 8.6%
Middle void %	10.5% +- 4.6%	1.9% +- 1.8%
Bottom void %	17.1% +- 14.5%	7.9% +- 2.3%
Average void %	9.7% +- 10.7%	5.6% +- 5.6%

[0048] As can be seen from the above table, using silane and diborane results in significantly reduced void percentage. Process C: multiple cycles of (B₂H₆ + SiH₄ mixture – Ar purge – WF₆) was used and resulted in an average void percentage of 7.7%, as compared to 9.7% for boron only.

10 **[0049]** Process details are shown in the table below.

	Parameter	Process A	Process B	Process C
Nucleation ALD	Pulse Sequence	5 cycles (B/B/B/W) All Charge Volume	5 cycles (B/S/W) All Charge Volume	5 cycles (B+S/W) All Charge Volume
	Temperature	300 C	275 C	275 C
	B ₂ H ₆ and SiH ₄ timing divert/line charge/ dose/purge	0/9/5/30	0/9/5/9	0/9/5/9
	WF ₆ timing divert/line charge/	2/0.8/10/30	0/4.5/10/30	0/4.5/10/30

	dose/purge			
	B2H6/SiH4/Ar/ WF6 flows(sccm)	1350/0/0/1350	450/450/900/1350	1350/150/1200/1350 (*Ar flowing only during SiH4 to fully charge the SiH4 charge volume)
Bulk ALD	Pulse Sequence	H/WF6		
	Cycle time (sec)	.77		
	Temp	430 C		
	# cycles	1200		

[0050] Film properties were measured for films deposited on planar substrate using Process D, E, or F to deposit the nucleation layer. Bulk deposition was the same for all processes.

- 5 Process D: multiple cycles of (B2H6 – Ar purge – WF6 – Ar purge); substrate temp during nucleation layer of 225°C

Process E: multiple cycles of (B2H6 – Ar purge – SiH4 – Ar purge – WF6); substrate temp during nucleation layer of 300°C

- 10 Process F: multiple cycles of (B2H6 – Ar purge – SiH4 – Ar purge – WF6); substrate temp during nucleation layer of 275°C

Process details are shown in the table below

	Parameter	Process D	Process E	Process F
Nucleation ALD	Pulse Sequence	5 cycles (B/B/B/W) All Charge Volume	5 cycles (B/S/W) All Charge Volume	5 cycles (B+S/W) All Charge Volume
	Temperature	225 C	300 C	275 C
	B2H6 flow	1350	450	450

	(sccm)			
	Ar with B ₂ H ₆ (sccm)	0	900	900
	SiH ₄ flow (sccm)	0	450	450
	Ar with SiH ₄ (sccm)	0	900	900
	WF ₆ flow (sccm)	1350	1350	1350
Bulk ALD	Pulse Sequence	H/WF ₆		
	Cycle time (sec)	.77		
	Temp	430 C		
	# cycles	1200		

[0051] Film (nuc + bulk) properties are shown in the table below

Property	Process D	Process E	Process F
Film Rs Cp (Ohms/sq)	11.17	10.32	10.99
Film Rs Mean (Ohms/sq)	11.39	9.68	10.41
Rs NU%	4.73	3.36	3.25
Resistivity	22.06	20.03	20.56
FSM Mean Stress	-627.51	64.7	-207.62
Thickness (Å)	188.37	194.16	187.1

[0052] The results in the above table show that film resistivity is improved by using the
5 boron-containing and silicon-containing reducing agent to form the nucleation layer.
Stress can be lowered by reducing temperature without compromising fill.

Apparatus

[0053] Any suitable chamber may be used to implement the disclosed embodiments. Example deposition apparatuses include various systems, e.g., ALTUS® and ALTUS® Max, available from Lam Research Corp., of Fremont, California, or any of a variety of other commercially available processing systems. In some embodiments, atomic layer deposition (ALD) may be performed at a first station that is one of two, five, or even more deposition stations positioned within a single deposition chamber. Thus, for example, a diborane (B₂H₆)/silane (SiH₄) co-flow and tungsten hexafluoride (WF₆) may be introduced in alternating pulses to the surface of the semiconductor substrate, at the first station, using an individual gas supply system that creates a localized atmosphere at the substrate surface. Another station may be used for tungsten bulk layer deposition. Two or more stations may be used to deposit tungsten in parallel processing. Alternatively a wafer may be indexed to have operations performed over two or more stations sequentially. In another example, diborane, silane, and tungsten-precursor doses may be introduced sequentially, optionally separated by purges, at a first station to deposit a nucleation layer. Still further, one or more of these reactant pulses may be performed at one or more additional stations such that the tungsten nucleation layer deposition is performed at multiple stations.

[0054] In some embodiments, a charge volumes (also referred to as charge vessels) are used to introduce the gas doses to the chamber. Figure 3 shows an example of such a system, in which separate charge volumes are used for silane and diborane. This allows the silane and diborane to be introduced separately to the chamber (either co-flowed or sequential doses) and prevents reactions from occurring prior to introduction.

[0055] Figure 4 is a schematic of a process system suitable for conducting deposition processes in accordance with embodiments. The system 400 includes a transfer module 403. The transfer module 403 provides a clean, pressurized environment to minimize risk of contamination of substrates being processed as they are moved between various reactor modules. Mounted on the transfer module 403 is a multi-station reactor 409 capable of performing ALD and CVD according to various embodiments. Multi-station reactor 409 may include multiple stations 411, 413, 415, and 417 that may sequentially perform operations in accordance with disclosed embodiments. For example, multi-

station reactor 409 may be configured such that station 411 performs a tungsten nucleation layer deposition using a chlorine-containing tungsten precursor or a fluorine-containing precursor, and station 413 performs an ALD tungsten deposition operation according to various embodiments. In some embodiments, station 415 may also form an
5 ALD tungsten deposition operation, and station 417 may perform a CVD operation.

[0056] Stations may include a heated pedestal or substrate support, one or more gas inlets or showerhead or dispersion plate. An example of a deposition station 700 is depicted in Figure 5, including substrate support 502 and showerhead 503. A heater may be provided in pedestal portion 501.

10 **[0057]** Returning to Figure 4, also mounted on the transfer module 503 may be one or more single or multi-station modules 407 capable of performing plasma or chemical (non-plasma) pre-cleans, other deposition operations, or etch operations. The module may also be used for various treatments to, for example, prepare a substrate for a deposition process. The system 400 also includes one or more wafer source modules 401, where
15 wafers are stored before and after processing. An atmospheric robot (not shown) in the atmospheric transfer chamber 419 may first remove wafers from the source modules 401 to loadlocks 421. A wafer transfer device (generally a robot arm unit) in the transfer module 403 moves the wafers from loadlocks 421 to and among the modules mounted on the transfer module 403.

20 **[0058]** In various embodiments, a system controller 429 is employed to control process conditions during deposition. The controller 429 will typically include one or more memory devices and one or more processors. A processor may include a CPU or computer, analog and/or digital input/output connections, stepper motor controller boards, etc.

[0059] The controller 429 may control all of the activities of the deposition apparatus.
25 The system controller 429 executes system control software, including sets of instructions for controlling the timing, mixture of gases, chamber pressure, chamber temperature, wafer temperature, radio frequency (RF) power levels, wafer chuck or pedestal position, and other parameters of a particular process. Other computer programs stored on memory devices associated with the controller 429 may be employed in some
30 embodiments.

[0060] Typically there will be a user interface associated with the controller 429. The user interface may include a display screen, graphical software displays of the apparatus and/or process conditions, and user input devices such as pointing devices, keyboards, touch screens, microphones, etc.

5 [0061] System control logic may be configured in any suitable way. In general, the logic can be designed or configured in hardware and/or software. The instructions for controlling the drive circuitry may be hard coded or provided as software. The instructions may be provided by "programming." Such programming is understood to include logic of any form, including hard coded logic in digital signal processors, application-specific
10 integrated circuits, and other devices which have specific algorithms implemented as hardware. Programming is also understood to include software or firmware instructions that may be executed on a general purpose processor. System control software may be coded in any suitable computer readable programming language.

[0062] The computer program code for controlling the germanium-containing reducing
15 agent pulses, hydrogen flow, and tungsten-containing precursor pulses, and other processes in a process sequence can be written in any conventional computer readable programming language: for example, assembly language, C, C++, Pascal, Fortran, or others. Compiled object code or script is executed by the processor to perform the tasks identified in the program. Also as indicated, the program code may be hard coded.

20 [0063] The controller parameters relate to process conditions, such as, for example, process gas composition and flow rates, temperature, pressure, cooling gas pressure, substrate temperature, and chamber wall temperature. These parameters are provided to the user in the form of a recipe, and may be entered utilizing the user interface.

[0064] Signals for monitoring the process may be provided by analog and/or digital input
25 connections of the system controller 429. The signals for controlling the process are output on the analog and digital output connections of the deposition apparatus 400.

[0065] The system software may be designed or configured in many different ways. For example, various chamber component subroutines or control objects may be written to control operation of the chamber components necessary to carry out the deposition
30 processes in accordance with the disclosed embodiments. Examples of programs or

sections of programs for this purpose include substrate positioning code, process gas control code, pressure control code, and heater control code.

[0066] In some implementations, a controller 429 is part of a system, which may be part of the above-described examples. Such systems can include semiconductor processing equipment, including a processing tool or tools, chamber or chambers, a platform or platforms for processing, and/or specific processing components (a wafer pedestal, a gas flow system, etc.). These systems may be integrated with electronics for controlling their operation before, during, and after processing of a semiconductor wafer or substrate. The electronics may be referred to as the “controller,” which may control various components or subparts of the system or systems. The controller 429, depending on the processing requirements and/or the type of system, may be programmed to control any of the processes disclosed herein, including the delivery of processing gases, temperature settings (e.g., heating and/or cooling), pressure settings, vacuum settings, power settings, radio frequency (RF) generator settings in some systems, RF matching circuit settings, frequency settings, flow rate settings, fluid delivery settings, positional and operation settings, wafer transfers into and out of a tool and other transfer tools and/or load locks connected to or interfaced with a specific system.

[0067] Broadly speaking, the controller may be defined as electronics having various integrated circuits, logic, memory, and/or software that receive instructions, issue instructions, control operation, enable cleaning operations, enable endpoint measurements, and the like. The integrated circuits may include chips in the form of firmware that store program instructions, digital signal processors (DSPs), chips defined as application specific integrated circuits (ASICs), and/or one or more microprocessors, or microcontrollers that execute program instructions (e.g., software). Program instructions may be instructions communicated to the controller in the form of various individual settings (or program files), defining operational parameters for carrying out a particular process on or for a semiconductor wafer or to a system. The operational parameters may, in some embodiments, be part of a recipe defined by process engineers to accomplish one or more processing steps during the fabrication of one or more layers, materials, metals, oxides, silicon, silicon dioxide, surfaces, circuits, and/or dies of a wafer.

[0068] The controller 429, in some implementations, may be a part of or coupled to a

computer that is integrated with, coupled to the system, otherwise networked to the system, or a combination thereof. For example, the controller 429 may be in the "cloud" or all or a part of a fab host computer system, which can allow for remote access of the wafer processing. The computer may enable remote access to the system to monitor
5 current progress of fabrication operations, examine a history of past fabrication operations, examine trends or performance metrics from a plurality of fabrication operations, to change parameters of current processing, to set processing steps to follow a current processing, or to start a new process. In some examples, a remote computer (e.g. a server) can provide process recipes to a system over a network, which may include
10 a local network or the Internet. The remote computer may include a user interface that enables entry or programming of parameters and/or settings, which are then communicated to the system from the remote computer. In some examples, the controller receives instructions in the form of data, which specify parameters for each of the processing steps to be performed during one or more operations. It should be understood
15 that the parameters may be specific to the type of process to be performed and the type of tool that the controller is configured to interface with or control. Thus as described above, the controller may be distributed, such as by including one or more discrete controllers that are networked together and working towards a common purpose, such as the processes and controls described herein. An example of a distributed controller for
20 such purposes would be one or more integrated circuits on a chamber in communication with one or more integrated circuits located remotely (such as at the platform level or as part of a remote computer) that combine to control a process on the chamber.

[0069] Without limitation, example systems may include a plasma etch chamber or module, a deposition chamber or module, a spin-rinse chamber or module, a metal plating
25 chamber or module, a clean chamber or module, a bevel edge etch chamber or module, a physical vapor deposition (PVD) chamber or module, a CVD chamber or module, an ALD chamber or module, an atomic layer etch (ALE) chamber or module, an ion implantation chamber or module, a track chamber or module, and any other semiconductor processing systems that may be associated or used in the fabrication and/or manufacturing of
30 semiconductor wafers.

[0070] As noted above, depending on the process step or steps to be performed by the

tool, the controller might communicate with one or more of other tool circuits or modules, other tool components, cluster tools, other tool interfaces, adjacent tools, neighboring tools, tools located throughout a factory, a main computer, another controller, or tools used in material transport that bring containers of wafers to and from tool locations and/or
5 load ports in a semiconductor manufacturing factory.

[0071] The controller 429 may include various programs. A substrate positioning program may include program code for controlling chamber components that are used to load the substrate onto a pedestal or chuck and to control the spacing between the substrate and other parts of the chamber such as a gas inlet and/or target. A process gas
10 control program may include code for controlling gas composition, flow rates, pulse times, and optionally for flowing gas into the chamber prior to deposition in order to stabilize the pressure in the chamber. A pressure control program may include code for controlling the pressure in the chamber by regulating, e.g., a throttle valve in the exhaust system of the chamber. A heater control program may include code for controlling the current to a
15 heating unit that is used to heat the substrate. Alternatively, the heater control program may control delivery of a heat transfer gas such as helium to the wafer chuck.

[0072] Examples of chamber sensors that may be monitored during deposition include mass flow controllers, pressure sensors such as manometers, and thermocouples located in the pedestal or chuck. Appropriately programmed feedback and control algorithms may
20 be used with data from these sensors to maintain desired process conditions.

[0073] The apparatus may include a gas manifold system, which provides line charges to the various gas distribution lines as shown schematically in Figure 4. Manifold 404 has an input 402 from a source of a tungsten-containing precursor gas (not shown), manifold 411 has an input 409 from a source of hydrogen or other reducing gas (not shown) and
25 manifold 421 has an input 419 from a source of inert purge gas (not shown). The manifolds 404, 411 and 421 provide the tungsten-containing precursor gas, reducing gas and purge gas to the deposition chamber through valved distribution lines, 405, 413 and 425 respectively. The various valves are opened or closed to provide a line charge, i.e., to pressurize the distribution lines. For example, to pressurize distribution line 405, valve 406
30 is closed to vacuum and valve 408 is closed. After a suitable increment of time, valve 408 is opened and the tungsten-containing precursor gas is delivered to the chamber. Charging

the tungsten precursor to a high pressure during ALD deposition of the bulk layer (e.g., to 400 Torr) can improve resistivity in some embodiments. After a suitable time for delivery of the gas, valve 408 is closed. The chamber can then be purged to a vacuum by opening of valve 406 to vacuum.

5 **[0074]** Similar processes are used to deliver the reducing gas and the purge gas. To introduce the reducing gas, for example, distribution line 413 is charged by closing valve 415 and closing valve 417 to vacuum. Opening of valve 415 allows for delivery of the reducing gas to the chamber. Similarly, to introduce the purge gas, distribution line 425 is charged by closing valve 427 and closing valve 423 to vacuum. Opening of valve 427 allows
10 for delivery of the argon or other inert purge gas to the chamber. The amount of time allowed for line charges changes the amount and timing of the initial delivery of the gas.

[0075] Figure 4 also shows vacuum pumps in which valves 406, 417 and 423, respectively, can be opened to purge the system. The supply of gas through the various distribution lines is controlled by a controller, such as a mass flow controller which is
15 controlled by a microprocessor, a digital signal processor or the like, that is programmed with the flow rates, duration of the flow, and the sequencing of the processes.

[0076] Note that the processes described above may require precise timing of valves and mass flow controllers (MFCs) supplying pulses of reagent to the semiconductor substrate during deposition. In one way to make this possible, valve and MFC commands are
20 delivered to embedded digital input-output controllers (IOC) in discrete packets of information containing instructions for all time-critical commands for all or a part of a deposition sequence. The ALTUS systems of Lam Research provide at least one IOC sequence. The IOCs can be physically located at various points in the apparatus; e.g., within the process module or on a stand-alone power rack standing some distance away
25 from the process module. There may be multiple IOCs in each module (e.g., 3 per module). With respect to the actual instructions included in a sequence, all commands for controlling valves and setting flow for MFCs (for all carrier and reactant gases) may be included in a single IOC sequence. This assures that the timing of all the devices is tightly controlled from an absolute standpoint and also relative to each other. There are typically
30 multiple IOC sequences running at any given time. This allows for, say, ALD to run at station 1-2 with all timing controlled for all the hardware components needed to deposit a ALD-

W nucleation layer at those stations. A second sequence might be running concurrently to deposit a tungsten bulk using the timing sequence described above at other deposition stations in the same module. The relative timing of the devices controlling the delivery of reagents to stations 3-4 is important within that group of devices, but the relative timing of the ALD process at stations 1-2 can be offset from the relative timing of stations 3-4. An IOC translates the information in a packetized sequence and delivers digital or analog command signals directly to MFC or pneumatic solenoid banks controlling the valves.

[0077] A pulse of tungsten-containing gas may be generated as follows. Initially, the system diverts WF₆ to a vacuum pump for a period of time while the MFC or other flow-controlling device stabilizes. This may be done for a period of between about 0.5 to 5 seconds in one example. Next, the system pressurizes the tungsten gas delivery manifold by closing both the divert outlet 406 and the outlet 408 to the deposition chamber. This may be done for a period of between about 0.1 and 5 seconds, for example, to create an initial burst of reagent when the outlet to the deposition chamber is opened. This is accomplished by opening outlet valve 408 for between about 0.1 and 10 seconds in one example. Thereafter, the tungsten-containing gas is purged from the deposition chamber using a suitable purge gas. The pulsed flow of other reagents may be done in a similar manner.

[0078] The foregoing describes implementation of disclosed embodiments in a single or multi-chamber semiconductor processing tool. The apparatus and process described herein may be used in conjunction with lithographic patterning tools or processes, for example, for the fabrication or manufacture of semiconductor devices, displays, LEDs, photovoltaic panels, and the like. Typically, though not necessarily, such tools/processes will be used or conducted together in a common fabrication facility. Lithographic patterning of a film typically includes some or all of the following steps, each step provided with a number of possible tools: (1) application of photoresist on a workpiece, i.e., substrate, using a spin-on or spray-on tool; (2) curing of photoresist using a hot plate or furnace or UV curing tool; (3) exposing the photoresist to visible or UV or x-ray light with a tool such as a wafer stepper; (4) developing the resist so as to selectively remove resist and thereby pattern it using a tool such as a wet bench; (5) transferring the resist pattern into an underlying film or workpiece by using a dry or plasma-assisted etching tool; and (6)

removing the resist using a tool such as an RF or microwave plasma resist stripper

- [0079]** Although the foregoing embodiments have been described in some detail for purposes of clarity of understanding, it will be apparent that certain changes and modifications may be practiced within the scope of the appended claims. It should be
- 5 noted that there are many alternative ways of implementing the processes, systems, and apparatus of the present embodiments. Accordingly, the present embodiments are to be considered as illustrative and not restrictive, and the embodiments are not to be limited to the details given herein.